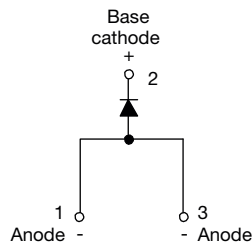


## Surface Mount Fast Soft Recovery Rectifier Diode, 8 A



DPAK (TO-252AA)



### FEATURES

- Glass passivated pellet chip junction
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Meets JESD 201 class 2 whisker test
- Flexible solution for reliable AC power rectification
- High surge, low  $V_F$  rugged blocking diode for DC charging stations
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
 COMPLIANT  
 HALOGEN  
**FREE**

### PRIMARY CHARACTERISTICS

$I_{F(AV)}$	8 A
$V_R$	1200 V
$V_F$ at $I_F$	1.3 V
$I_{FSM}$	150 A
$t_{rr}$	80 ns
$T_J$ max.	150 °C
Package	DPAK (TO-252AA)
Circuit configuration	Single
Snap factor	0.6

### APPLICATIONS

- On-board and off-board EV / HEV battery chargers
- Renewable energy inverters

### DESCRIPTION

The VS-8EWF12SLHM3 fast soft recovery rectifier series has been optimized for combined short reverse recovery time, low forward voltage drop and low leakage current.

The glass passivation ensures stable reliable operation in the most severe temperature and power cycling conditions.

### MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Sinusoidal waveform	8	A
$V_{RRM}$		1200	V
$I_{FSM}$		150	A
$V_F$	8 A, $T_J = 25$ °C	1.3	V
$t_{rr}$	1 A, 100 A/ $\mu$ s	80	ns
$T_J$	Range	-40 to +150	°C

### VOLTAGE RATINGS

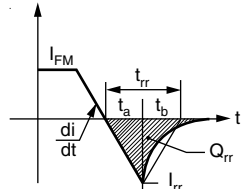
PART NUMBER	$V_{RRM}$ , MAXIMUM PEAK REVERSE VOLTAGE V	$V_{RSM}$ , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	$I_{RRM}$ AT 150 °C mA
VS-8EWF12SLHM3	1200	1300	4

### ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$	$T_C = 96$ °C, 180° conduction half sine wave	8	A
Maximum peak one cycle non-repetitive surge current	$I_{FSM}$	10 ms sine pulse, rated $V_{RRM}$ applied	125	
		10 ms sine pulse, no voltage reapplied	150	
Maximum $I^2t$ for fusing	$I^2t$	10 ms sine pulse, rated $V_{RRM}$ applied	78	A <sup>2</sup> s
		10 ms sine pulse, no voltage reapplied	110	
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	$t = 0.1$ ms to 10 ms, no voltage reapplied	1100	A <sup>2</sup> $\sqrt{s}$

ELECTRICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop	$V_{FM}$	8 A, $T_J = 25^\circ\text{C}$		1.3	V
Forward slope resistance	$r_t$	$T_J = 150^\circ\text{C}$		25.6	$\text{m}\Omega$
Threshold voltage	$V_{F(TO)}$			0.93	V
Maximum reverse leakage current	$I_{RM}$	$V_R = \text{Rated } V_{RRM}$	$T_J = 25^\circ\text{C}$	0.1	mA
			$T_J = 150^\circ\text{C}$	4	

RECOVERY CHARACTERISTICS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Reverse recovery time	$t_{rr}$	$I_F$ at 8 $A_{pk}$ 25 $A/\mu\text{s}$ $T_J = 25^\circ\text{C}$	270	ns
Reverse recovery current	$I_{rr}$		4.2	A
Reverse recovery charge	$Q_{rr}$		1	$\mu\text{C}$
Snap factor	S		0.6	



THERMAL - MECHANICAL SPECIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	$T_J, T_{Stg}$		-40 to +150	$^\circ\text{C}$
Maximum thermal resistance, junction to case	$R_{thJC}$	DC operation	2.5	$^\circ\text{C}/\text{W}$
Typical thermal resistance, junction to ambient (PCB mount)	$R_{thJA}^{(1)}$		50	
Approximate weight			1	g
			0.03	oz.
Marking device		Case style DPAK (TO-252AA)	8EWF12SH	

**Note**

(1) When mounted on 1" square (650 mm<sup>2</sup>) PCB of FR-4 or G-10 material 4 oz. (140  $\mu\text{m}$ ) copper 40  $^\circ\text{C}/\text{W}$

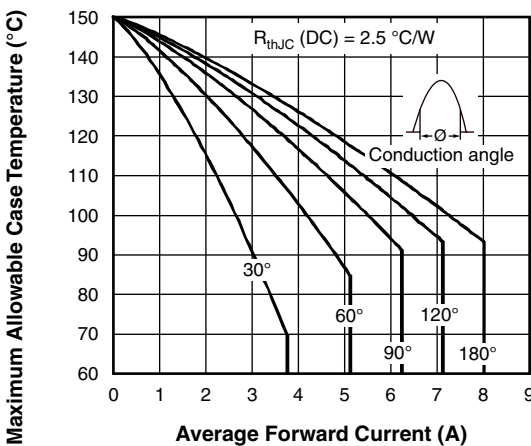


Fig. 1 - Current Rating Characteristics

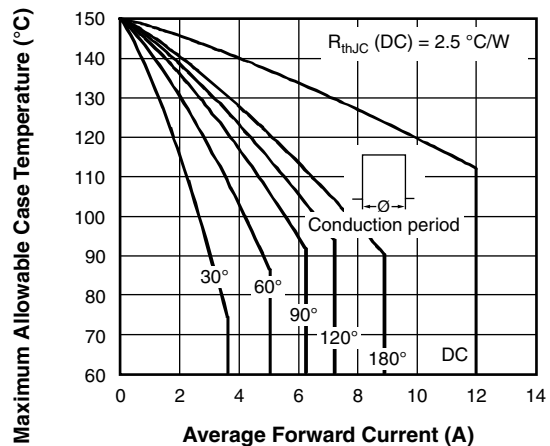


Fig. 2 - Current Rating Characteristics

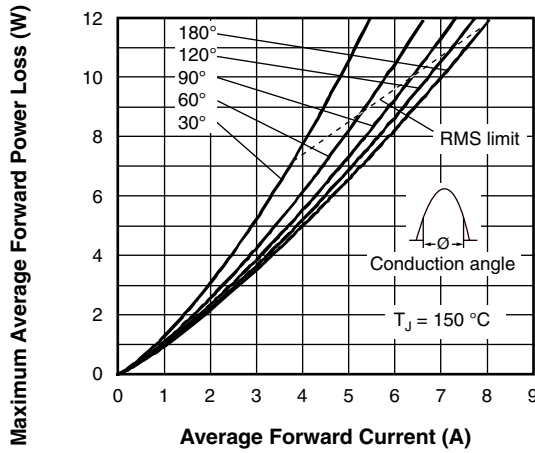


Fig. 3 - Forward Power Loss Characteristics

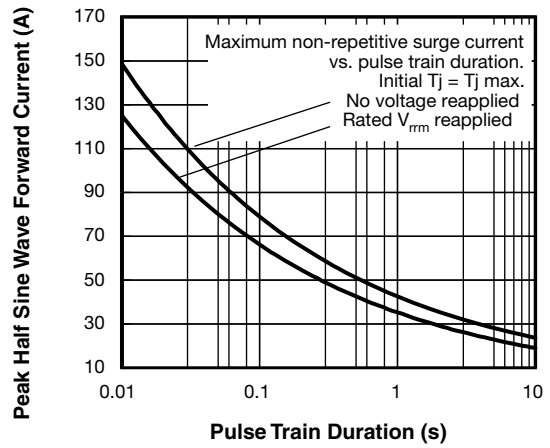


Fig. 6 - Maximum Non-Repetitive Surge Current

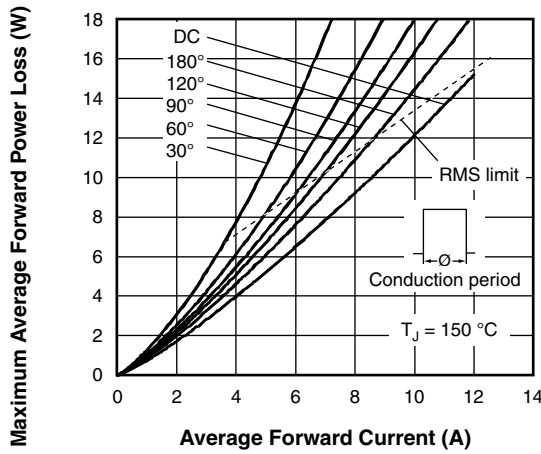


Fig. 4 - Forward Power Loss Characteristics

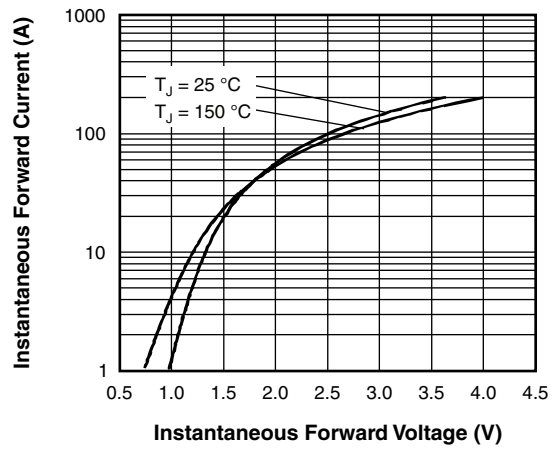


Fig. 7 - Forward Voltage Drop Characteristics

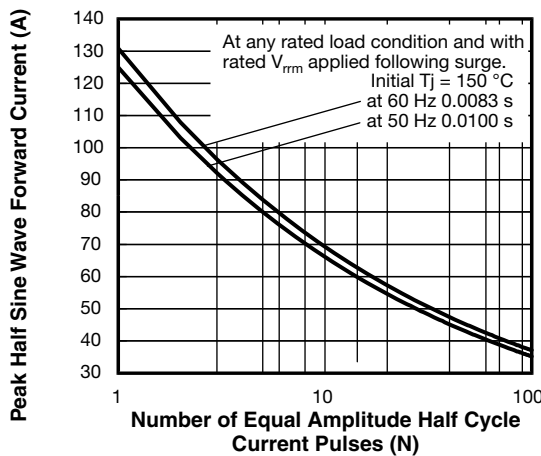


Fig. 5 - Maximum Non-Repetitive Surge Current

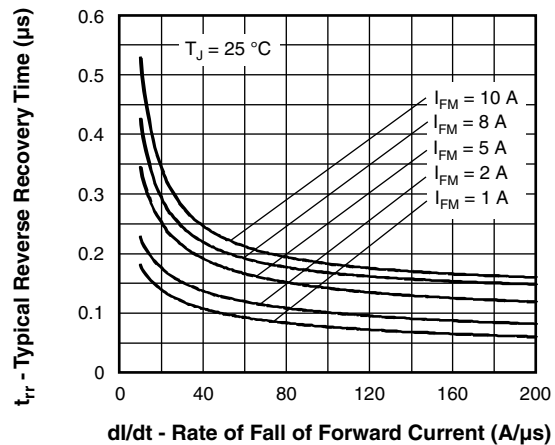


Fig. 8 - Recovery Time Characteristics,  $T_J = 25\text{ }^\circ\text{C}$

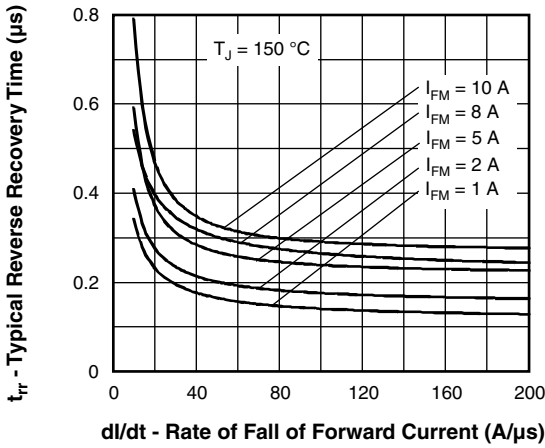


Fig. 9 - Recovery Time Characteristics,  $T_J = 150\text{ }^\circ\text{C}$

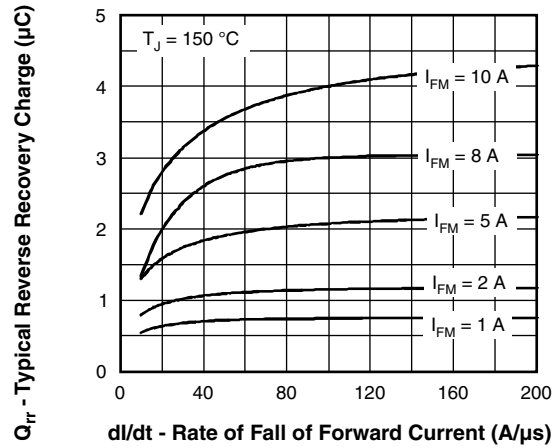


Fig. 11 - Recovery Charge Characteristics,  $T_J = 150\text{ }^\circ\text{C}$

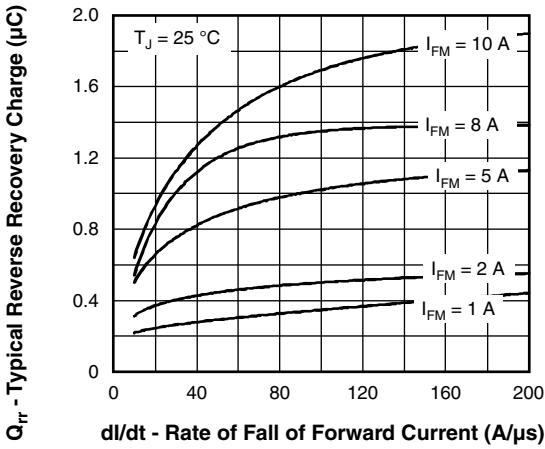


Fig. 10 - Recovery Charge Characteristics,  $T_J = 25\text{ }^\circ\text{C}$

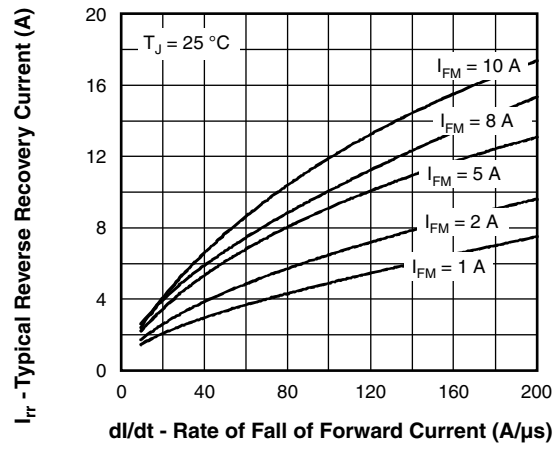


Fig. 12 - Recovery Current Characteristics,  $T_J = 25\text{ }^\circ\text{C}$

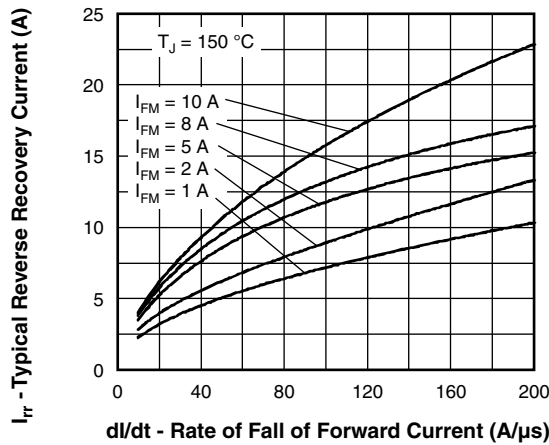
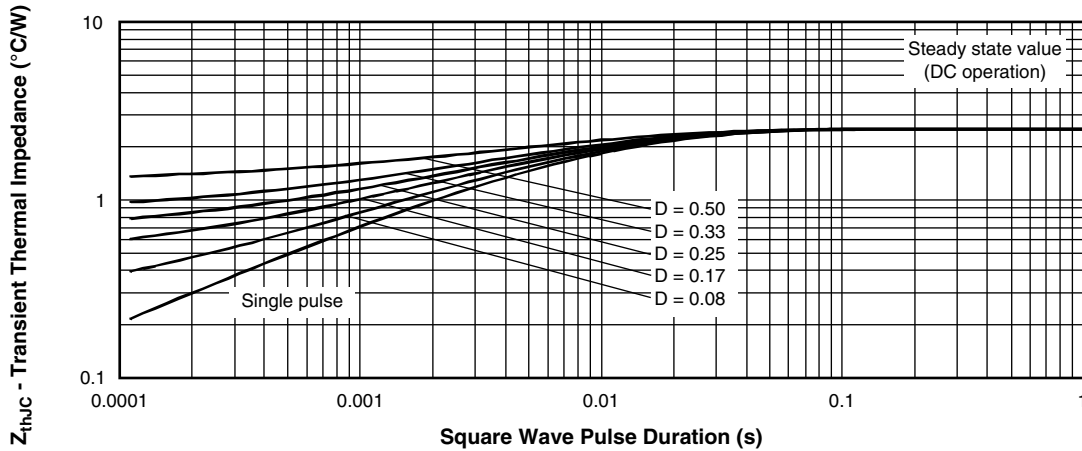


Fig. 13 - Recovery Current Characteristics,  $T_J = 150\text{ }^\circ\text{C}$


 Fig. 14 - Thermal Impedance  $Z_{thJC}$  Characteristics

**ORDERING INFORMATION TABLE**

Device code	<b>VS-</b>	<b>8</b>	<b>E</b>	<b>W</b>	<b>F</b>	<b>12</b>	<b>S</b>	<b>L</b>	<b>H</b>	<b>M3</b>
	①	②	③	④	⑤	⑥	⑦	⑧	⑨	⑩
	<b>1</b>	-	Vishay Semiconductors product							
	<b>2</b>	-	Current rating (8 = 8 A)							
	<b>3</b>	-	Circuit configuration: E = single							
	<b>4</b>	-	Package: W = DPAK (TO-252AA)							
	<b>5</b>	-	Type of silicon: F = fast soft recovery rectifier							
	<b>6</b>	-	Voltage code x 100 = $V_{RRM}$ — <b>12 = 1200 V</b>							
	<b>7</b>	-	S = surface mountable							
	<b>8</b>	-	L = tape and reel (left oriented), for different orientation contact factory							
	<b>9</b>	-	H = AEC-Q101 qualified							
	<b>10</b>	-	Environmental digit: M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free							

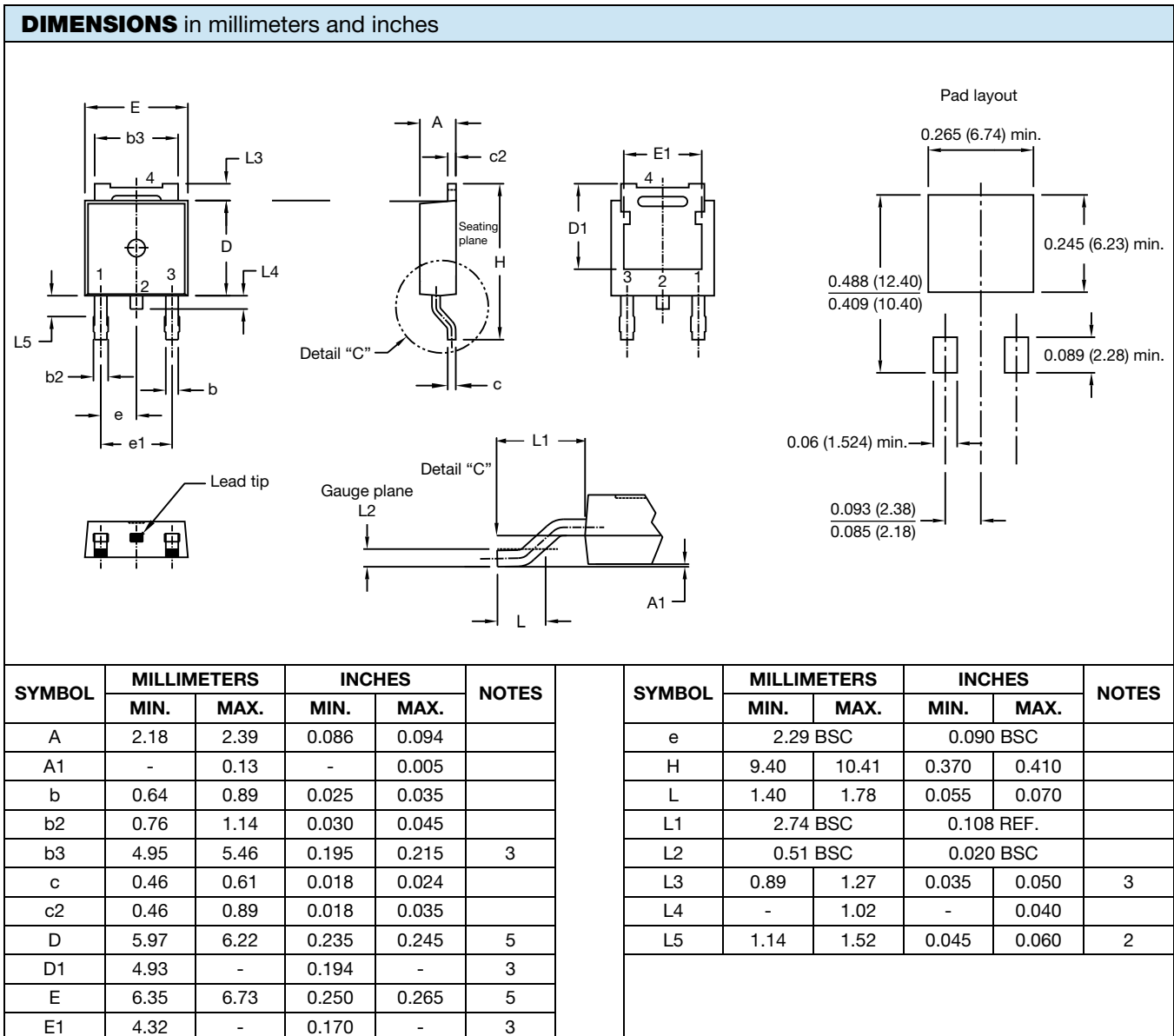
**ORDERING INFORMATION** (Example)

PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-8EWF12SLHM3	3000	3000	13" diameter reel

**LINKS TO RELATED DOCUMENTS**

Dimensions	<a href="http://www.vishay.com/doc?95519">www.vishay.com/doc?95519</a>
Part marking information	<a href="http://www.vishay.com/doc?95518">www.vishay.com/doc?95518</a>
Packaging information	<a href="http://www.vishay.com/doc?96495">www.vishay.com/doc?96495</a>
SPICE model	<a href="http://www.vishay.com/doc?97057">www.vishay.com/doc?97057</a>

### DPAK (TO-252AA)



**Notes**

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Dimensions D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (5) Outline conforms to JEDEC® outline TO-252AA, except for D1 dimension



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